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April 1st, 2010

Renesas Electronics Corporation

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Note : Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

Renesas Technology Corp. Customer Support Dept. April 1, 2003





MITSUBISHI MICROCOMPUTERS M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

DESCRIPTION

The M37735EHBXXXFP is a single-chip microcomputer using the 7700 Family core. This single-chip microcomputer has a CPU and a bus interface unit. The CPU is a 16-bit parallel processor that can be an 8-bit parallel processor, and the bus interface unit enhances the memory access efficiency to execute instructions fast. This microcomputer also includes a 32 kHz oscillation circuit, in addition to the PROM, RAM, multiple-function timers, serial I/O, A-D converter, and so on.

The M37735EHBXXXFP has the same function as the M37735MHBXXXFP except that the built-in ROM is PROM. For program development, the M37735EHBFS with erasable ROM that is housed in a windowed ceramic LCC is also provided. (Refer to the basic function blocks description.)

FEATURES

Number of basic	c instructions	103
Memory size	PROM	124 Kbytes
	RAM	3968 bytes
Instruction exec	ution time	
The factost inst	ruction at 25 MHz frequency	160 nc

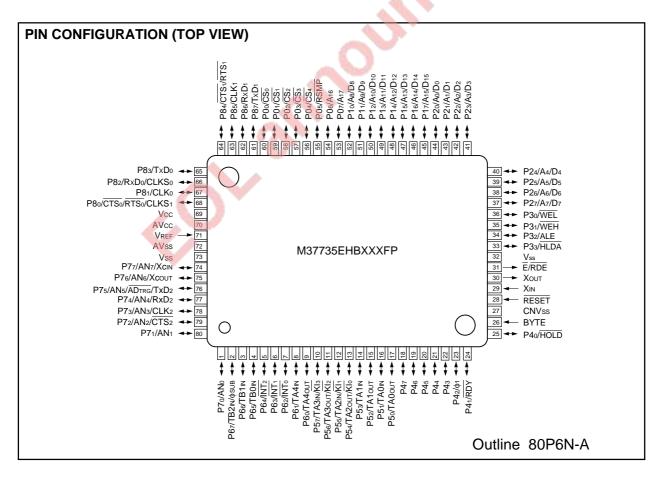
The fastest instruction at 25 MHz frequency 160 ns

APPLICATION

Control devices for general commercial equipment such as office automation, office equipment, and so on.

Control devices for general industrial equipment such as communication equipment, and so on.

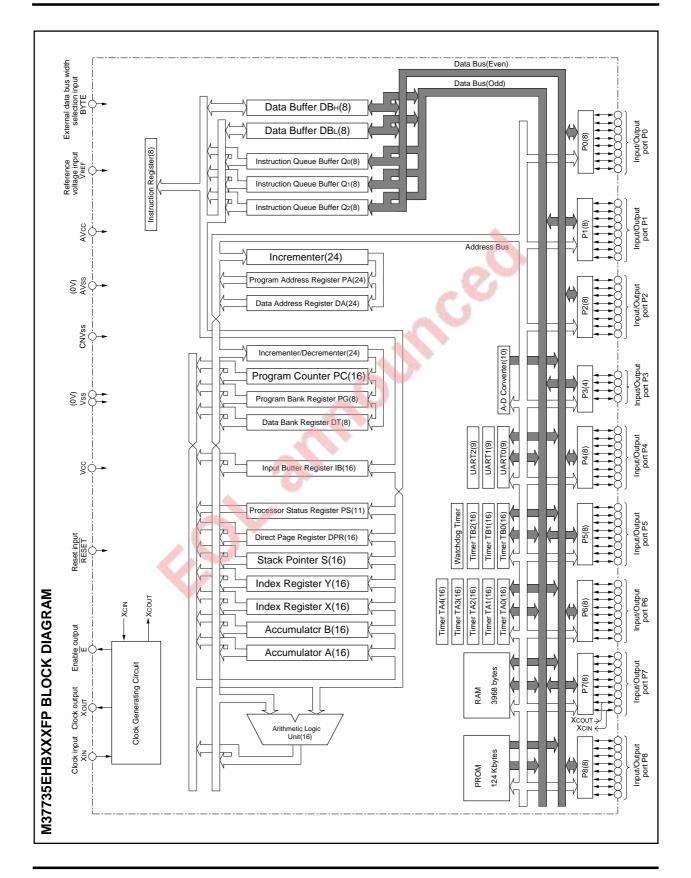
Note. Do not use the windowed EPROM version for mass production, because it is a tool for program development (for evaluation).





MITSUBISHI MICROCOMPUTERS

M37735EHBXXXFP M37735EHBFS







M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

FUNCTIONS OF M37735EHBXXXFP

	Parameter	Functions		
Number of basic instructions		103		
Instruction execution time		160 ns (the fastest instruction at external clock 25 MHz frequency)		
Memory size	PROM	124 Kbytes		
Memory size	RAM	3968 bytes		
lanut/Output norte	P0 – P2, P4 – P8	8-bit × 8		
Input/Output ports	P3	4-bit X 1		
Multi function timoro	TA0, TA1, TA2, TA3, TA4	16-bit X 5		
Multi-function timers	TB0, TB1, TB2	16-bit X 3		
Serial I/O		(UART or clock synchronous serial I/O) X 3		
A-D converter		10-bit X 1 (8 channels)		
Watchdog timer		12-bit X 1		
Interrunte		3 external types, 16 internal types		
Interrupts		Each interrupt can be set to the priority level $(0 - 7.)$		
Clock generating circuit		2 circuits built-in (externally connected to a ceramic resonator or a quartz-crystal oscillator)		
Supply voltage		5 V ± 10%		
Power dissipation		47.5 mW (at external clock 25 MHz frequency)		
•	Input/Output voltage	5 V		
Input/Output characteristic	Output current	5 mA		
Memory expansion		Maximum 1 Mbytes		
Operating temperature range		-20 to 85 °C		
Device structure		CMOS high-performance silicon gate process		
Deekees	M37735EHBXXXFP	80-pin plastic molded QFP (80P6N-A)		
Package	M37735EHBFS	80-pin ceramic LCC (with a window) (80D0)		



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M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

PIN DESCRIPTION

Pin	Name	Input/Output	Functions
Vcc,	Power source		Apply 5 V \pm 10% to Vcc and 0 V to Vss.
Vss			
CNVss	CNVss input	Input	This pin controls the processor mode. Connect to Vss for the single-chip mode and the memory expansion mode, and to Vcc for the microprocessor mode.
RESET	Reset input	Input	When "L" level is applied to this pin, the microcomputer enters the reset state.
Xin	Clock input	Input	These are pins of main-clock generating circuit. Connect a ceramic resonator or a quartz- crystal oscillator between XIN and XOUT. When an external clock is used, the clock source should
Хоит	Clock output	Output	be connected to the XIN pin, and the XOUT pin should be left open.
Ē	Enable output	Output	This pin functions as the enable signal output pin which indicates the access status in the internal bus. In the memory expansion mode or the microprocessor mode, this pin functions as the RDE signal output pin.
BYTE	External data bus width selection input	Input	In the memory expansion mode or the microprocessor mode, this pin determines whether the external data bus has an 8-bit width or a 16-bit width. The data bus has a 16-bit width when "L" signal is input and an 8-bit width when "H" signal is input.
AVcc, AVss	Analog power source input		Power source input pin for the A-D converter. Externally connect AVcc to Vcc and AVss to Vss.
VREF	Reference voltage input	Input	This is reference voltage input pin for the A-D converter.
P00 – P07	I/O port P0	I/O	In the single-chip mode, port P0 becomes an 8-bit I/O port. An I/O direction register is available so that each pin can be programmed for input or output. These ports are in the input mode when reset. In the memory expansion mode or the microprocessor mode, these pins output $\overline{CS_0} - \overline{CS_4}$, RSMP
P10-P17	I/O port P1	I/O	signals, and address (A ₁₆ , A ₁₇). In the single-chip mode, these pins have the same functions as port P0. When the BYTE pin is set to "L" in the memory expansion mode or the microprocessor mode and external data bus has a 16-bit width, high-order data (D ₈ – D ₁₅) is input/output or an address (A ₈ – A ₁₅) is output. When the BYTE pin is "H" and an external data bus has an 8-bit width, only address (A ₈ – A ₁₅) is output.
P20 – P27	I/O port P2	I/O	In the single-chip mode, these pins have the same functions as port P0. In the memory expansion mode or the microprocessor mode, low-order data $(D_0 - D_7)$ is input/output or an address $(A_0 - A_7)$ is output.
P30 – P33	I/O port P3	I/O	In the single-chip mode, these pins have the same function as port P0. In the memory expansion mode or the microprocessor mode, WEL, WEH, ALE, and HLDA signals are output.
P40 – P47	I/O port P4	I/O	In the single-chip mode, these pins have the same functions as port P0. In the memory expansion mode or the microprocessor mode, P40, P41, and P42 become HOLD and RDY input pins, and a clock ϕ_1 output pin, respectively. Functions of the other pins are the same as in the single-chip mode. However, in the memory expansion mode, P42 can be selected as an I/O port.
P50 – P57	I/O port P5	I/O	In addition to having the same functions as port P0 in the single-chip mode, these pins also function as I/O pins for timers A0 to A3 and input pins for key input interrupt input ($\overline{K_{10}} - \overline{K_{13}}$).
P60 – P67	I/O port P6	1/0	In addition to having the same functions as port P0 in the single-chip mode, these pins also function as I/O pins for timer A4, input pins for external interrupt input ($\overline{INT_0} - \overline{INT_2}$) and input pins for timers B0 to B2. P67 also functions as a sub-clock ϕ_{SUB} output pin.
P70 – P77	I/O port P7	1/0	In addition to having the same functions as port P0 in the single-chip mode, these pins function as input pins for A-D converter. P72 to P75 also function as I/O pins for UART2. Additionally, P76 and P77 have the function as the output pin (XCOUT) and the input pin (XCIN) of the sub-clock (32 kHz) oscillation circuit, respectively. When P76 and P77 are used as the XCOUT and XCIN pins, connect a resonator or an oscillator between the both.
P80 - P87	I/O port P8	I/O	In addition to having the same functions as port P0 in the single-chip mode, these pins also function as I/O pins for UART 0 and UART 1.



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MITSUBISHI MICROCOMPUTERS

M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

Pin	Name	Input/Output	Functions
Vcc, Vss	Power supply		Supply 5V±10% to Vcc and 0V to Vss.
CNVss	VPP input	Input	Connect to VPP when programming or verifing.
BYTE	VPP input	Input	Connect to VPP when programming or verifing.
RESET	Reset input	Input	Connect to Vss.
XIN	Clock input	Input	Connect a ceramic resonator between XIN and XOUT.
Хоит	Clock output	Output	
E	Enable output	Output	Keep open.
AVcc, AVss	Analog supply input		Connect AVcc to Vcc and AVss to Vss.
Vref	Reference voltage input	Input	Connect to Vss.
P00 – P07	Address input (A0 – A7)	Input	Port P0 functions as the lower 8 bits address input (A0 – A7).
P10 – P17	Address input (A8 – A15)	Input	Port P1 functions as the higher 8 bits address input (A8 – A15).
P20 – P27	Data I/O (D0 – D7)	I/O	Port P2 functions as the 8 bits data bus(D0 – D7).
P30	Address input (A16)	Input	P30 functions as the most significant bit address input (A16).
P31 – P33	Input port P3	Input	Connect to Vss.
P40 – P47	Input port P4	Input	Connect to Vss.
P50 – P57	Control signal input	Input	P50, P51 and P52 function as PGM, OE and CE input pins respectively. Connect P53, P54, P55 and P56 to Vcc. Connect P57 to Vss.
P60 – P67	Input port P6	Input	Connect to Vss.
P70 – P77	Input port P7	Input	Connect to Vss.
P80 – P87	Input port P8	Input	Connect to Vss.



MITSUBISHI MICROCOMPUTERS

M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

BASIC FUNCTION BLOCKS

The M37735EHBXXXFP has the same functions as the M37735MHBXXXFP except for the following:

- (1) The built-in ROM is PROM.
- (2) The status of bit 3 of the oscillation circuit control register 1 (address $6F_{16}$) at a reset is different.
- (3) The usage condition of bit 3 of the oscillation circuit control register 1 is different.

(4) Part of the processor mode selection method is different.

Accordingly, refer to the basic function blocks description in the M37735MHBXXXFP except for Figure 1 (bit configuration of oscillation circuit control register 1), Figure 3 (microcomputer internal status during reset), and Table 1 (microprocessor mode selection method).

In the M37735EHBXXXFP, bit 3 of the oscillation circuit control register 1 must be "0". (Refer to Figure 1.) Bit 3 is "1" at a reset. Accordingly,

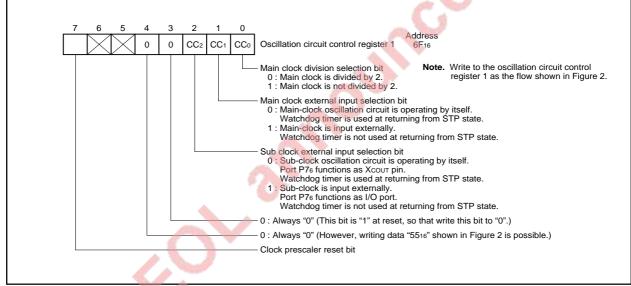
write "0" to bit 3 in the single-chip mode after reset.

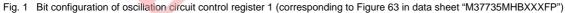
Figure 2 shows how to write data in oscillation circuit control register 1.

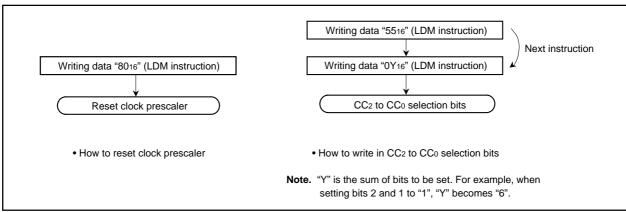
In the M37735EHBXXXFP, the microprosessor mode cannot be selected by connecting the CNVss pin to Vcc. Connect the CNVss pin to Vss and start the microcomputer's operating from the single-chip mode.

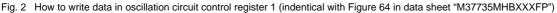
Table 1. Relationship between CNVss pin input level and processor modes

CNVss	Mode	Description
Vss	Single-chip Memory expansion Microprocessor	Single-chip mode upon starting after reset. Each mode can be selected by changing the processor mode bits by software.











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M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

	Address		Address
Port P0 direction register	(0416)••• 0016	Watchdog timer frequency selection flag	(6116)
Port P1 direction register	(0516) 0016	Memory allocation control register	(6316)
Port P2 direction register	(0816) 0016	UART2 transmit/receive mode register	(6416)
Port P3 direction register	(0916)	UART2 transmit/receive control register 0	(6816)
Port P4 direction register	(0C16)••• 0016	UART2 transmit/receive control register 1	(6916)••• 0 0 0 0 0 0 1 0
Port P5 direction register	(0D16)••• 0016	Oscillation circuit control register 0	(6C16)••• 0 0 0 0 0 1
Port P6 direction register	(1016) 0016	Port function control register	(6D16)••• 0016
Port P7 direction register	(1116)••• 0016	Serial transmit control register	(6E16)••• 0 0
Port P8 direction register	(1416)••• 0016	Oscillation circuit control register 1	(6F16)•••• 0 X 0 1 0 0 0
A-D control register 0	(1E16)••• 0 0 0 0 0 ? ? ?	A-D/UART2 trans./rece. interrupt control register	(7016)
A-D control register 1	(1F16)••• 0 0 0 1 1	UART 0 transmission interrupt control registre	
UART 0 transmit/receive mode register	(3016) 0016	UART 0 receive interrupt control register	(7216)
UART 1 transmit/receive mode register	(3816)••• 0016	UART 1 transmission interrupt control register	er (7316) X X 0 0 0 0
UART 0 transmit/receive	(3416) 0 0 0 0 1 0 0 0	UART 1 receive interrupt control register	(7416)
control register 0 UART 1 transmit/receive control register 0	(3C16) 0 0 0 0 1 0 0 0	Timer A0 interrupt control register	(7516)
UART 0 transmit/receive	(3516) 0 0 0 0 0 0 1 0	Timer A1 interrupt control register	(7616)
control register 1 UART 1 transmit/receive	(3D16)••• 0 0 0 0 0 0 1 0	Timer A2 interrupt control register	(7716)
control register 1 Count start flag	(4016)••• 0016	Timer A3 interrupt control register	(7816)
One- shot start flag	(4216)	Timer A4 interrupt control register	(7916)
Up-down flag	(4416)••• 0016	Timer B0 interrupt control register	(7A16)
Timer A0 mode register	(5616)	Timer B1 interrupt control register	(7B16)
Timer A1 mode register	(5716)	Timer B2 interrupt control register	(7C16)••• 0 0 0 0
Timer A2 mode register	(5816) 0016	INTo interrupt control register	(7D16)••• 0 0 0 0 0 0 0
Timer A3 mode register	(5916) 0016	INT1 interrupt control register	(7E16)
Timer A4 mode register	(5A16) 0016	INT2/Key input interrupt control register	(7F16)••• 0 0 0 0 0 0
Timer B0 mode register	(5B16) 0 0 1 0 0 0 0 0	Processor status register (PS)	000??0001??
Timer B1 mode register	(5C16) 0 0 1 0 0 0 0	Program bank register (PG)	0016
Timer B2 mode register	(5D16) 0 0 1 0 0 0 0	Program counter (PCH)	Content of FFFF16
Processor mode register 0	(5E16)••• 0016	Program counter (PCL)	Content of FFFE16
Processor mode register 1	(5F16)•••	Direct page register (DPR)	000016
Watchdog timer register	(6016)••• FFF16	Data bank register (DT)	0016

Fig. 3 Microcomputer internal status during reset



MITSUBISHI MICROCOMPUTERS

M37735EHBXXXFP **M37735EHBFS**

PROM VERSION OF M37735MHBXXXFP

EPROM MODE

The M37735EHBXXXFP features an EPROM mode in addition to its normal modes. When the RESET signal level is "L", the chip automatically enters the EPROM mode. Table 2 list the correspondence between pins and Figure 4 shows the pin connections in the EPROM mode.

The EPROM mode is the 1M mode for the EPROM that is equivalent to the M5M27C101K.

When in the EPROM mode, ports P0, P1, P2, P30, P50, P51, P52, CNVss, and BYTE are used for the EPROM (equivalent to the

Table 2 Pin function in EPROM mode

			-
	M37735EHBXXXFP	M5M27C101K	
Vcc	Vcc	Vcc]
Vpp	CNVss, BYTE	Vpp	
Vss	Vss	Vss	
Address input		A0 – A16	07
Data I/O	Port P2	D0 – D7	
CE	P52	CE	
OE	P51	OE	
PGM	P50	PGM	
		1-an	

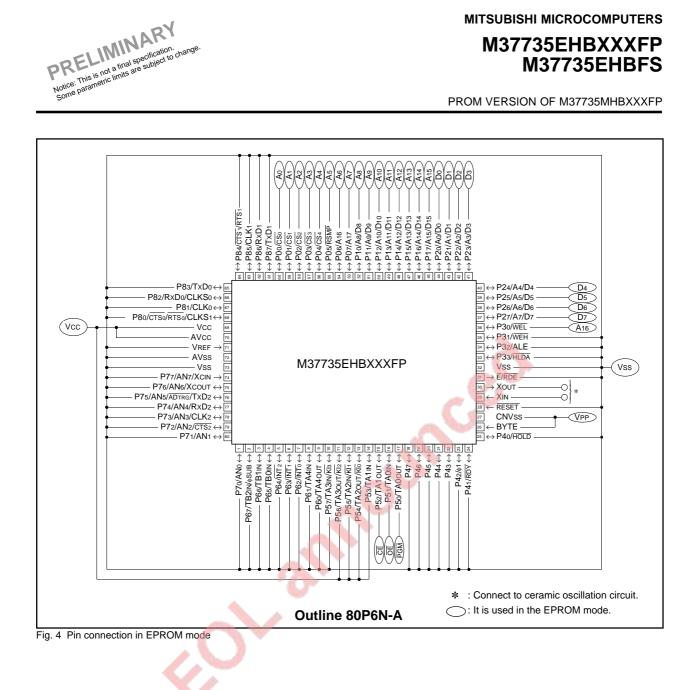
M5M27C101K).

When in this mode, the built-in PROM can be programmed or read from using these pins in the same way as with the M5M27C101K. This chip does not have Device Identifier Mode, so that set the corresponding program algorithm. The program area should specify address 0100016 - 1FFFF16.

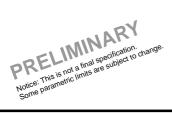
Connect the clock which is either ceramic resonator or external clock to XIN pin and XOUT pin.



M37735EHBXXXFP **M37735EHBFS**







M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

FUNCTION IN EPROM MODE 1M mode (equivalent to the M5M27C101K)

Reading

To read the EPROM, set the \overline{CE} and \overline{OE} pins to a "L" level. Input the address of the data (A₀ – A₁₆) to be read, and the data will be output to the I/O pins D₀ – D₇. The data I/O pins will be floating when either the \overline{CE} or \overline{OE} pins are in the "H" state.

Programming

Programming must be performed in 8 bits by a byte program. To program to the EPROM, set the \overline{CE} pin to a "L" level and the \overline{OE} pin to a "H" level. The CPU will enter the programming mode when 12.5 V is applied to the VPP pin. The address to be programmed to is selected with pins A0 – A16, and the data to be programmed is input to pins D0 – D7. Set the PGM pin to a "L" level to being programming.

Erasing

To erase data on this chip, use an ultraviolet light source with a 2537 Angstrom wave length. The minimum radiation power necessary for erasing is 15 J/cm^2 .

Programming operation

To program the M37735EHBXXXFP, first set Vcc = 6 V, VPP = 12.5 V, and set the address to 0100016. Apply a 0.2 ms programming pulse, check that the data can be read, and if it cannot be read OK, repeat the procedure, applying a 0.2 ms programming pulse and checking that the data can be read until it can be read OK. Record the accumulated number of pulse applied (X) before the data can be read OK, and then write the data again, applying a further once this number of pulses (0.2 X X ms).

When this series of programming operations is complete, increment the address, and continue to repeat the procedure above until the last address has been reached.

Finally, when all addresses have been programmed, read with Vcc = VPP = 5 V (or Vcc = VPP = 5.5 V).

Table 2.	I/O signal in each mode	
----------	-------------------------	--

Pin Mode	CE	OE	PGM	Vpp	Vcc	Data I/O
Read-out	VIL	VIL	Х	5 V	5 V	Output
Output	VIL	Vін	Х	5 V	5 V	Floating
Disable	Vih	Х	Х	5 V	5 V	Floating
Programming	Vi∟	Vін	VIL	12.5 V	6 V	Input
Programming Verify	VIL	VIL	Vін	12.5 V	6 V	Output
Program Disable	Vih	Vін	Vін	12.5 V	6 V	Floating

Note 1 : An X indicates either VIL or VIH.

Programming operation (equivalent to the M5M27C101K)

AC ELECTRICAL CHARACTERISTICS (Ta = 25 ± 5 °C, Vcc = 6 V ± 0.25 V, VPP = 12.5 ± 0.3 V, unless otherwise noted)

Symbol	Parameter	Test conditions		11-14		
Symbol			Min.	Тур.	Max.	Unit
tAS	Address setup time		2			μs
tOES	OE setup time		2			μs
tDS	Data setup time		2			μs
tah	Address hold time		0			μs
tDH	Data hold time		2			μs
tDFP	Output enable to output float delay		0		130	ns
tvcs	Vcc setup time		2			μs
tVPS	VPP setup time		2			μs
tPW	PGM pulse width		0.19	0.2	0.21	ms
tOPW	PGM over program pulse width		0.19		5.25	ms
tCES	CE setup time		2			μs
tOE	Data valid from OE				150	ns

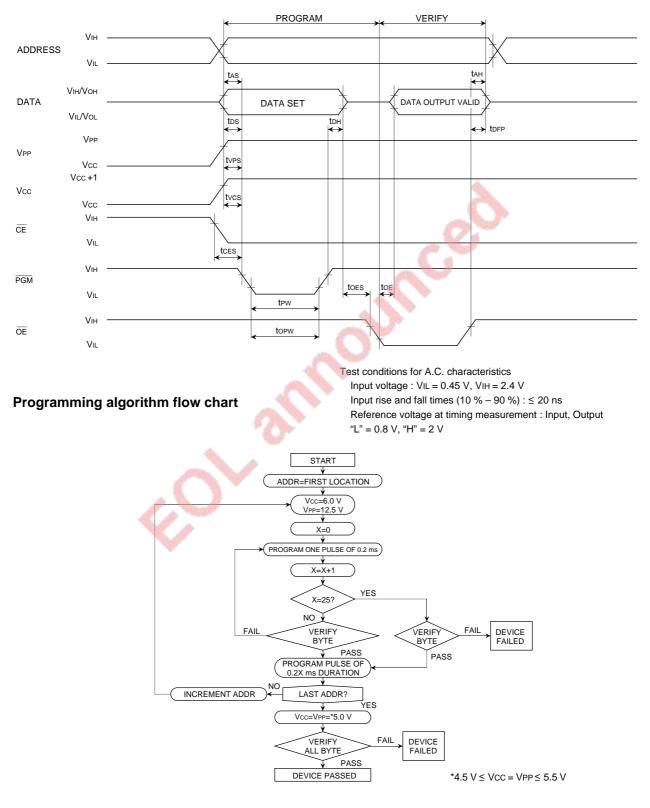




M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

AC waveforms





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PROM VERSION OF M37735MHBXXXFP

SAFETY INSTRUCTIONS

- (1) Sunlight and fluorescent lamp contain light that can erase written information. When using in read mode, be sure to cover the transparent glass portion with a seal or other materials (ceramic package product).
- (2) Mitsubishi Electric corp. provides the seal for covering the transparent glass. Take care that the seal does not touch the read pins (ceramic package product).
- (3) Clean the transparent glass before erasing. Fingers' fat and paste disturb the passage of ultraviolet rays and may affect badly the erasure capability (ceramic package product).
- (4) A high voltage is used for programming. Take care that overvoltage is not applied. Take care especially at power on.
- (5) The programmable M37735EHBFP that is shipped in blank is also provided. For the M37735EHBFP, Mitsubishi Electric corp. does not perform PROM programming test and screening following the assembly processes. To improve reliability after programming, performing programming and test according to the flow below before use is recommended.

ADDRESSING MODES

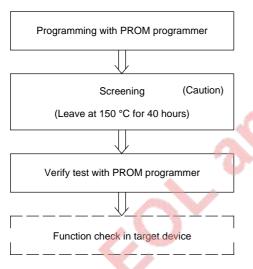
The M37735EHBXXXFP has 28 powerful addressing modes. Refer to the MITSUBISHI SEMICONDUCTORS DATA BOOK SINGLE-CHIP 16-BIT MICROCOMPUTERS for the details of each addressing mode.

MACHINE INSTRUCTION LIST

The M37735EHBXXXFP has 103 machine instructions. Refer to the MITSUBISHI SEMICONDUCTORS DATA BOOK SINGLE-CHIP 16-BIT MICROCOMPUTERS for details.

DATA REQUIRED FOR PROM ORDERING

Please send the following data for writing to PROM. (1) M37735EHBXXXFP writing to PROM order confirmation form (2) 80P6N mark specification form (3) ROM data (EPROM 3 sets)



Caution : Never expose to 150 °C exceeding 100 hours.



PRELIMINARY Notice: This is not a final specification. Notice: This is not a final specification. Some parametric limits are subject to che

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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Power source voltage		-0.3 to +7	V
AVcc	Analog power source voltage		-0.3 to +7	V
Vi	Input voltage RESET, CNVss, BYTE		-0.3 to +12 (Note)	V
Vı	Input voltage P00 – P07, P10 – P17, P20 – P27, P30 – P33, P40 – P47, P50 – P57, P60 – P67, P70 – P77, P80 – P87, VREF, XIN		-0.3 to Vcc + 0.3	V
Vo	Output voltage P00 - P07, P10 - P17, P20 - P27, P30 - P33, P40 - P47, P50 - P57, P60 - P67, P70 - P77, P80 - P87, Xour, Ē		-0.3 to Vcc + 0.3	V
Pd	Power dissipation	Ta = 25 °C	300	mW
Topr	Operating temperature		-20 to +85	°C
Tstg	Storage temperature		-40 to +150	°C

Note. When the EPROM is programmed, input voltage of pins CNVss and BYTE is 13 V respectively.

RECOMMENDED OPERATING CONDITIONS (Vcc = 5 V ± 10%, Ta = -20 to +85 °C, unless otherwise noted)

Symbol	Parameter		Limits		Unit
Symbol	raidilietei	Min.	Тур.	Max.	
Vcc	Power source voltage f(XIN) : Operating	4.5	5.0	5.5	
VCC	f(XiN) : Stopped, f(XciN) = 32.768 kHz	2.7		5.5	V
AVcc	Analog power source voltage		Vcc		V
Vss	Power source voltage		0		V
AVss	Analog power source voltage		0		V
Vih	High-level input voltage P00 – P07, P30 – P33, P40 – P47, P50 – P57, P60 – P P70 – P77, P80 – P87, XIN, RESET, CNVss, BYTE, XCIN (Note			Vcc	V
Viн	High-level input voltage P10 – P17, P20 – P27 (in single-chip mode)	0.8 Vcc		Vcc	V
Vih	High-level input voltage P10 – P17, P20 – P27 (in memory expansion mode and microprocessor mode)	0.5 Vcc		Vcc	V
VIL	Low-level input voltage P00 – P07, P30 – P33, P40 – P47, P50 – P57, P60 – P6 P70 – P77, P80 – P87, XIN, RESET, CNVss, BYTE, XCIN (Note			0.2Vcc	V
VIL	Low-level input voltage P10 – P17, P20 – P27 (in single-chip mode)	0		0.2Vcc	V
VIL	Low-level input voltage P10 – P17, P20 – P27 (in memory expansion mode and microprocessor mode)	0		0.16Vcc	V
IOH(peak)	High-level peak output current P00 – P07, P10 – P17, P20 – P27, P30 – P33, P40 – P47, P50 – P57, P60 – P67, P70 – P77, P80 – P87			-10	mA
IOH(avg)	High-level average output current P00 – P07, P10 – P17, P20 – P27, P30 – P33 P40 – P47, P50 – P57, P60 – P67, P70 – P77 P80 – P87	· .		-5	mA
IOL(peak)	Low-level peak output current P00 – P07, P10 – P17, P20 – P27, P30 – P33, P40 – P43, P54 – P57, P60 – P67, P70 – P77, P80 – P87			10	mA
IOL(peak)	Low-level peak output current P44 – P47, P50 – P53			20	mA
IOL(avg)	Low-level average output current P00 – P07, P10 – P17, P20 – P27, P30 – P33 P40 – P43, P54 – P57, P60 – P67, P70 – P77 P80 – P87	·		5	mA
IOL(avg)	Low-level average output current P44 – P47, P50 – P53			15	mA
f(XIN)	Main-clock oscillation frequency (Note 4)			25	MHz
f(XCIN)	Sub-clock oscillation frequency		32.768	50	kHz

Notes 1. Average output current is the average value of a 100 ms interval.

2. The sum of IOL(peak) for ports P0, P1, P2, P3, and P8 must be 80 mA or less,

the sum of IOH(peak) for ports P0, P1, P2, P3, and P8 must be 80 mA or less,

the sum of IOL(peak) for ports P4, P5, P6, and P7 must be 100 mA or less, and

the sum of IOH(peak) for ports P4, P5, P6, and P7 must be 80 mA or less.

3. Limits VIH and VIL for XCIN are applied when the sub clock external input selection bit = "1".

4. The maximum value of $f(X_{IN}) = 12.5$ MHz when the main clock division selection bit = "1".





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O mark al	Demonster	Testereditions		Limits		
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Uni
	High-level output voltage P00 – P07, P10 – P17, P20 – P27,					
Vон	P33, P40 – P47, P50 – P57,	Iон = –10 mA	3			V
	P60 – P67, P70 – P77, P80 – P87					
Vон	High-level output voltage P00 – P07, P10 – P17, P20 – P27, P33	Іон = -400 μА	4.7			V
Vон	High-level output voltage P30 – P32	Iон = -10 mA	3.1			
VOIT		Існ = –400 µА	4.8			- V
Vон	High-level output voltage E	Iон = -10 mA	3.4			
VOIT		Іон = -400 μА	4.8			- V
Vol	Low-level output voltage P00 – P07, P10 – P17, P20 – P27, P33, P40 – P43, P54 – P57, P60 – P67, P70 – P75, P80 – P87	IoL = 10 mA			2	v
Vol	Low-level output voltage P44 – P47, P50 – P53	IoL = 20 mA			2	V
Vol	Low-level output voltage P00 – P07, P10 – P17, P20 – P27, P33	IoL = 2 mA	0		0.45	V
Vol	Low-level output voltage P30 – P32	IoL = 10 mA	100 600		1.9	v
/OL	Low-level oulput voltage P30 – P32	IoL = 2 mA	10		0.43	1 V
Vol	Low-level output voltage E	IoL = 10 mA			1.6	v
VOL	Low-level output voltage E	IoL = 2 mA			0.4	
Vt+ – Vt-	Hysteresis HOLD, RDY, TAOIN – TA4IN, TBOIN – TB2IN, INT0 – INT2, ADTRG, CTS0, CTS1, CTS2, CLK0, CLK1, CLK2, KI0 – KI3		0.4		1	v
Vt+ – Vt-	Hysteresis RESET		0.2		0.5	V
Vt+ – Vt–	Hysteresis XIN		0.1		0.4	V
Vt+ – Vt–	Hysteresis Xcin (When external clock is input)		0.1		0.4	V
Ін	High-level input current P00 – P07, P10 – P17, P20 – P27, P30 – P33, P40 – P47, P50 – P57, P60 – P67, P70 – P77, P80 – P87, XIN, RESET, CNVss, BYTE	Vi = 5 V			5	μA
lı∟	Low-level input current P00 – P07, P10 – P17, P20 – P27, P30 – P33, P40 – P47, P50 – P53, P60, P61, P65 – P67, P70 – P77, P80 – P87, XIN, RESET, CNVss, BYTE	VI = 0 V			-5	μA
liL	Low-level input current P54 – P57, P62 – P64	VI = 0 V, without a pull-up transistor			-5	μA
		VI = 0 V, with a pull-up transistor	-0.25	-0.5	-1.0	mA
/RAM	RAM hold voltage	When clock is stopped.	2			V

ELECTRICAL CHARACTERISTICS (Vcc = 5 V, Vss = 0 V, Ta = -20 to 85 °C, f(XIN) = 25 MHz, unless otherwise noted)



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Symbol	Parameter	Test conditions				Unit	
Gymbol							Max.
Icc			Vcc = 5 V, $f(X_{IN}) = 25$ MHz (square waveform), $(f(f_2) = 12.5$ MHz), $f(X_{CIN}) = 32.768$ kHz, in operating (Note 1)		9.5	19	mA
			Vcc = 5 V, $f(X_{IN}) = 25$ MHz (square waveform), $(f(f_2) = 1.5625$ MHz), $f(X_{CIN}) = Stopped$, in operating (Note 1)		1.3	2.6	mA
	Power source current	In single-chip mode, output pins are open, and other pins are Vss.	$ \begin{array}{l} Vcc = 5V, \\ f(XiN) = 25 \mbox{ MHz} (square waveform), \\ f(XciN) = 32.768 \mbox{ kHz}, \\ when a WIT instruction is executed (Note 2) \end{array} $		10	20	μA
			Vcc = 5 V, f(XIN) : Stopped, f(XCIN) : 32.768 kHz, in operating (Note 3)	00	50	100	μA
			Vcc = 5 V, f(XIN) : Stopped, f(XCIN) : 32.768 kHz, when a WIT instruction is executed (Note 4)		5	10	μΑ
			Ta = 25 °C, when clock is stopped			1	μA
			Ta = 85 °C, when clock is stopped			20	μA

ELECTRICAL CHARACTERISTICS (Vcc = 5 V, Vss = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Notes 1. This applies when the main clock external input selection bit = "1", the main clock division selection bit = "0", and the signal output stop bit = "1".

2. This applies when the main clock external input selection bit = "1" and the system clock stop bit at wait state = "1".

- 3. This applies when CPU and the clock timer are operating with the sub clock (32.768 kHz) selected as the system clock.
- 4. This applies when the XCOUT drivability selection bit = "0" and the system clock stop bit at wait state = "1".

A-D CONVERTER CHARACTERISTICS

PRELIMINARY Notice: This is not a final specification. Some parametric limits are subject to change

(Vcc = AVcc = 5 V, Vss = AVss = 0 V, Ta = -20 to 85 °C, f(XIN) = 25 MHz (Note), unless otherwise noted)

Symbol	Parameter	Test conditions		Unit		
			Min.	Тур.	Max.	Unit
—	Resolution	VREF = VCC			10	Bits
—	Absolute accuracy	VREF = VCC			± 3	LSB
RLADDER	Ladder resistance	VREF = VCC	10		25	kΩ
t CONV	Conversion time		9.44			μs
Vref	Reference voltage		2		Vcc	V
VIA	Analog input voltage		0		Vref	V

Note. This applies when the main clock division selection bit = "0" and $f(f_2) = 12.5$ MHz.



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TIMING REQUIREMENTS (Vcc = 5 V ± 10%, Vss = 0 V, Ta = -20 to 85 °C, f(XIN) = 25 MHz, unless otherwise noted (Note)) **Notes 1.** This applies when the main clock division selection bit = "0" and f(f2) = 12.5 MHz.

Inits applies when the main clock division selection bit = 0 and i(i2) = 12.5 Mr
 Input signal's rise/fall time must be 100 ns or less, unless otherwise noted.

External clock input

Symbol	Parameter	Lir	1.1.0.14	
		Min.	Max.	Unit
tc	External clock input cycle time (Note 3)	40		ns
tw(H)	External clock input high-level pulse width (Note 4)	15		ns
tw(L)	External clock input low-level pulse width (Note 4)	15		ns
tr	External clock rise time		8	ns
tf	External clock fall time		8	ns

Notes 3. When the main clock division selection bit = "1", the minimum value of tc = 80 ns.

4. When the main clock division selection bit = "1", values of tw(H) / tc and tw(L) / tc must be set to values from 0.45 through 0.55.

Single-chip mode

Symbol	Parameter		Limits		
Gymbol	l'alanciel	Min.	Max.	Unit	
tsu(P0D–E)	Port P0 input setup time	60		ns	
tsu(P1D–E)	Port P1 input setup time	60		ns	
tsu(P2D-E)	Port P2 input setup time	60		ns	
tsu(P3D–E)	Port P3 input setup time	60		ns	
tsu(P4D–E)	Port P4 input setup time	60		ns	
tsu(P5D–E)	Port P5 input setup time	60		ns	
tsu(P6D–E)	Port P6 input setup time	60		ns	
tsu(P7D–E)	Port P7 input setup time	60		ns	
tsu(P8D–E)	Port P8 input setup time	60		ns	
th(E–P0D)	Port P0 input hold time	0		ns	
th(E–P1D)	Port P1 input hold time	0		ns	
th(E–P2D)	Port P2 input hold time	0		ns	
th(E–P3D)	Port P3 input hold time	0		ns	
th(E–P4D)	Port P4 input hold time	0		ns	
th(E–P5D)	Port P5 input hold time	0		ns	
th(E–P6D)	Port P6 input hold time	0		ns	
th(E–P7D)	Port P7 input hold time	0		ns	
th(E–P8D)	Port P8 input hold time	0		ns	

Memory expansion mode and microprocessor mode

Symbol	Parameter	Lir	Unit	
	r aldificter	Min.	Max.	
tsu(D–RDE)	Data input setup time	32		ns
tsu(RDY–φ1)	RDY input setup time	55		ns
tsu(HOLD–φ1)	HOLD input setup time	55		ns
th(RDE–D)	Data input hold time	0		ns
th(\phi1-RDY)	RDY input hold time	0		ns
th(φ1–HOLD)	HOLD input hold time	0		ns





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Timer A input (Count input in event counter mode)

Symbol	parameter		Limits		
	parameter	Min.	Max.	Unit	
tc(TA)	TAin input cycle time	80		ns	
tw(TAH)	TAin input high-level pulse width	40		ns	
tw(TAL)	TAin input low-level pulse width	40		ns	

Timer A input (Gating input in timer mode)

Symbol	parameter		Limits		
	parameter	Min.	Max.	Unit	
tc(TA)	TAin input cycle time (Note)	320		ns	
tw(TAH)	TAin input high-level pulse width (Note)	160		ns	
tw(TAL)	TAin input low-level pulse width (Note)	160		ns	

Note. Limits change depending on f(XIN). Refer to "DATA FORMULAS" on page 19.

Timer A input (External trigger input in one-shot pulse mode)

Symbol	parameter		imits	Unit
Symbol		Min.	Max.	Unit
tc(TA)	TAiin input cycle time (Note)	320		ns
tw(TAH)	TAiın input high-level pulse width	80		ns
tw(TAL)	TAil input low-level pulse width	80		ns

Note. Limits change depending on f(XIN). Refer to "DATA FORMULAS" on page 19.

Timer A input (External trigger input in pulse width modulation mode)

Symbol	parameter			Lir	Unit		
	parameter	Min.	Max.				
tw(TAH)	TAilN input high-level pulse width	1			80		ns
tw(TAL)	TAilN input low-level pulse width	10			80		ns
						•	

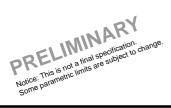
Timer A input (Up-down input in event counter mode)

Symbol	parameter	Lir	Unit	
		Min.	Max.	Unit
tc(UP)	TAiout input cycle time	2000		ns
tw(UPH)	TAiout input high-level pulse width	1000		ns
tw(UPL)	TAiout input low-level pulse width	1000		ns
tsu(UP–TIN)	TAiout input setup time	400		ns
th(TiN–UP)	TAiout input hold time	400		ns

Timer A input (Two-phase pulse input in event counter mode)

Symbol	parameter		Limits		
	parameter	Min.	Max.	Unit	
tc(TA)	TAjiN input cycle time	800		ns	
tsu(TAjın−TAjou⊤)	TAjın input setup time	200		ns	
tsu(TAjout-TAjin)	TAjou⊤ input setup time	200		ns	





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Timer B input (Count input in event counter mode)

Symbol	Parameter	Lir	Unit	
Gymbol		Min.	Max.	
tc(TB)	TBin input cycle time (one edge count)	80		ns
tw(TBH)	TBin input high-level pulse width (one edge count)	40		ns
tw(TBL)	TBin input low-level pulse width (one edge count)	40		ns
tc(TB)	TBin input cycle time (both edges count)	160		ns
tw(TBH)	TBin input high-level pulse width (both edges count)	80		ns
tw(TBL)	TBin input low-level pulse width (both edges count)	80		ns

Timer B input (Pulse period measurement mode)

Symbol	Parameter		Limits		
Gymbol			Max.	Unit	
tc(TB)	TBin input cycle time (Note)	320		ns	
tw(TBH)	TBin input high-level pulse width (Note)	160		ns	
tw(TBL)	TBin input low-level pulse width (Note)	160		ns	

Note. Limits change depending on f(XIN). Refer to "DATA FORMULAS" on page 19.

Timer B input (Pulse width measurement mode)

Symbol	Parameter	Limits		Unit
	raidilielei	Min.	Max.	
tc(TB)	TBin input cycle time (Note)	320		ns
tw(TBH)	TBin input high-level pulse width (Note)	160		ns
tw(TBL)	TBin input low-level pulse width (Note)	160		ns

Note. Limits change depending on f(XIN). Refer to "DATA FORMULAS" on page 19.

A-D trigger input

Symbol	Parameter	Lir	Unit	
Gymbol	i circinetei	Min.	Max.	
tc(AD)	ADTRG input cycle time (minimum allowable trigger)	1000		ns
tw(ADL)	ADTRG input low-level pulse width	125		ns

Serial I/O

Symbol	Parameter	Lir	Unit	
Symbol	Falanetei	Min.	Max.	Unit
tc(CK)	CLKi input cycle time	200		ns
tw(CKH)	CLKi input high-level pulse width	100		ns
tw(CKL)	CLKi input low-level pulse width	100		ns
td(C–Q)	TxDi output delay time		80	ns
th(C–Q)	TxDi hold time	0		ns
tsu(D–C)	RxDi input setup time	30		ns
th(C–D)	RxDi input hold time	90		ns

External interrupt INTi input, key input interrupt Kli input

Symbol	Parameter	Lir	Unit	
		Min.	Max.	
tw(INH)	INTi input high-level pulse width	250		ns
tw(INL)	INTi input low-level pulse width	250		ns
tw(KIL)	Kii input low-level pulse width	250		ns





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DATA FORMULAS

Timer A input (Gating input in timer mode)

Symbol	Parameter	Limits	Unit	
Cymbol		Min.	Max.	Unit
tc(TA)	TAin input cycle time	$\frac{8 \times 10^9}{2 \cdot f(f_2)}$		ns
tw(TAH)	TAin input high-level pulse width	$\frac{4 \times 10^9}{2 \cdot f(f_2)}$		ns
tw(TAL)	TAin input low-level pulse width	$\frac{4 \times 10^9}{2 \cdot f(f_2)}$		ns

Timer A input (External trigger input in one-shot pulse mode)

Symbol	Parameter	Limits	Linit	
		Min.	Max.	Unit
tc(TA)	TAin input cycle time	$\frac{8 \times 10^9}{2 \cdot f(f_2)}$		ns

Timer B input (In pulse period measurement mode or pulse width measurement mode)

Symbol	Parameter	Limits	Unit	
Gymbol		Min.	Max.	Unit
tc(TB)	TBin input cycle time	$\frac{8 \times 10^9}{2 \cdot f(f_2)}$		ns
tw(TBH)	TBin input high-level pulse width	$\frac{4 \times 10^9}{2 \cdot f(f_2)}$		ns
tw(TBL)	TBin input low-level pulse width	$\frac{4 \times 10^9}{2 \cdot f(f_2)}$		ns

Note. f(f2) represents the clock f2 frequency.

For the relation to the main clock and sub clock, refer to Table 10 in data sheet "M37735MHBXXXFP".



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SWITCHING CHARACTERISTICS (Vcc = 5 V ± 10%, Vss = 0 V, Ta = -20 to 85°C, f(XIN) = 25 MHz (Note), unless otherwise noted)

Single-chip mode

Symbol	Parameter	Test conditions	Lir	Unit	
Cymbol		rest conditions	Min.	Max.	
td(E–P0Q)	Port P0 data output delay time			80	ns
td(E–P1Q)	Port P1 data output delay time			80	ns
td(E–P2Q)	Port P2 data output delay time			80	ns
td(E–P3Q)	Port P3 data output delay time			80	ns
td(E–P4Q)	Port P4 data output delay time	Fig. 5		80	ns
td(E–P5Q)	Port P5 data output delay time			80	ns
td(E–P6Q)	Port P6 data output delay time			80	ns
td(E–P7Q)	Port P7 data output delay time			80	ns
td(E-P8Q)	Port P8 data output delay time			80	ns

Note. This applies when the main clock division selection bit = "0" and f(f₂) = 12.5 MHz.

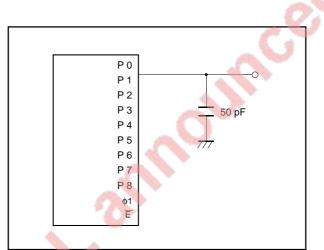


Fig. 5 Measuring circuit for ports P0 - P8 and \$\phi1



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Memory expansion mode and microprocessor mode

(Vcc = 5 V ± 10%, Vss = 0 V, Ta = -20 to 85 °C, f(XIN) = 25 MHz (Note 1), unless otherwise noted)

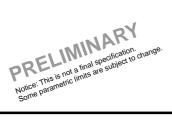
Symbol	Parameter	(Note 2)	Test	Lin	nits	Unit
Cymbol	i alameter	Wait mode	conditions	Min.	Max.	Unit
td(CS–WE) td(CS–RDE)	Chip-select output delay time	No wait Wait 1		12		ns
td(CS=KDE)		Wait 0		87		ns
th(WE–CS) th(RDE–CS)	Chip-select hold time			4		ns
td(An–WE)	Address output delay time	No wait Wait 1		12		ns
td(An–RDE)		Wait 0		87		ns
td(A–WE)	Address output delay time	No wait Wait 1		12		ns
td(A–RDE)		Wait 0		75		ns
th(WE–An) th(RDE–An)	Address hold time			18		ns
tw(ALE)	ALE pulse width	No wait Wait 1	00	22		ns
		Wait 0	8	57		ns
tsu(A–ALE)	Address output setup time	No wait Wait 1	Fig. 5	5		ns
		Wait 0		45		ns
th(ALE–A)	Address hold time	No wait Wait 1		9		ns
		Wait 0		15		ns
td(ALE–WE) td(ALE–RDE)	ALE output delay time	No wait Wait 1		4		ns
td(ALE=KDE)		Wait 0		10		ns
td(WE–DQ)	Data output delay time				45	ns
th(WE–DQ)	Data hold time	NI		18		ns
tw(WE)	WEL/WEH pulse width	No wait Wait 1 Wait 0		50 130		ns ns
tpxz(RDE–DZ)	Floating start delay time	waito			5	ns
tpzx(RDE-DZ)	Floating release delay time			20	Ŭ	ns
		No wait		48		ns
tw(RDE)	RDE pulse width	Wait 1 Wait 0		128		ns
td(RSMP–WE) td(RSMP–RDE)	RSMP output delay time			10		ns
th(\u00f61-RSMP)	RSMP hold time			0		ns
td(WE-φ1) td(RDE-φ1)	φ1 output delay time			0	18	ns
td(htbl://ull	HLDA output delay time				50	ns

Notes 1. This applies when the main clock division selection bit = "0" and $f(f_2) = 12.5$ MHz.

2. No wait : Wait bit = "1".

Wait 1 : The external memory area is accessed with wait bit = "0" and wait selection bit = "1". Wait 0 : The external memory area is accessed with wait bit = "0" and wait selection bit = "0".





M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

Memory expansion mode and microprocessor mode

Bus timing data formulas (Vcc = 5 V ± 10%, Vss = 0 V, Ta = -20 to 85 °C, f(XIN) = 25 MHz (Max., Note1), unless otherwise noted)

Symbol	Parameter		Limits		Linit
Cymbol		Wait mode	Min.	Max.	Unit
		No wait	$\frac{1 \times 10^9}{2000} - 28$		ns
td(CS-WE)	Chip-select output delay time	Wait 1	$2 \cdot f(f_2)$		
td(CS–RDE)		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 33$		ns
th(WE–CS) th(RDE–CS)	Chip-select hold time		4		ns
		No wait	$\frac{1 \times 10^9}{-28}$ - 28		ns
td(An–WE)	Address output delay time	Wait 1	$2 \cdot f(f_2)$		113
td(An–RDE)		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 33$		ns
		No wait	$\frac{1 \times 10^9}{2000} - 28$		ns
td(A–WE)	Address output delay time	Wait 1	$2 \cdot f(t_2)$		115
td(A–RDE)		Wait 0	$\frac{3 \times 10^9}{2 \cdot f(f_2)} - 45$		ns
th(WE–An) th(RDE–An)	Address hold time	0	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 22$		ns
		No wait	1 × 109		
tw(ALE)	ALE pulse width	Wait 1	$\frac{1 \times 10^{5}}{2 \cdot f(f_{2})} - 18$		ns
(W(ALE)	ALE pulse width		2 × 109		
		Wait 0	$\frac{2 \times 10}{2 \cdot f(f_2)} - 23$		ns
	Address output setup time	No wait	$\frac{1 \times 10^9}{-35}$ - 35		ns
tsu(A–ALE)		Wait 1	2 · f(f2)		
100() () (22)		Wait 0	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 35$		ns
	Address hold time	No wait	9		ns
th(ALE-A)		Wait 1	-		
		Wait 0	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 25$		ns
		No wait	4		ns
td(ALE–WE)	ALE output delay time	Wait 1			113
td(ALE–RDE)		Wait 0	$\frac{1 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
td(WE–DQ)	Data output delay time			45	ns
th(WE–DQ)	Data hold time		$\frac{1 \times 10^9}{2}$ - 22		ns
			2 · f(f2)		
		No wait	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 30$		ns
tw(WE)	WEL/WEH pulse width	Wait 1	4 X 10 ⁹		
		Wait 0	$\frac{1}{2 \cdot f(f_2)} - 30$		ns
tpxz(RDE–DZ)	Floating start delay time			5	ns
tpzx(RDE–DZ)	Floating release delay time		$\frac{1 \times 10^9}{2000000000000000000000000000000000000$		ns
,			$2 \cdot f(f_2)$		
tw(RDE)	RDE pulse width	No wait	$\frac{2 \times 10^9}{2 \cdot f(f_2)} - 32$		ns
(KDE)		Wait 1 Wait 0	$\frac{4 \times 10^9}{2 \cdot f(f_2)} - 32$		ns
td(RSMP-WE)	RSMP output delay time		1 X 10 ⁹ 20		ns
td(RSMP-RDE)			2 · f(f2)		
th(\$1-RSMP)	RSMP hold time		0		ns
td(WE–φ1) td(RDE–φ1)	φ1 output delay time		0	18	ns
ια(ΚΝΕ-ΦΊ)				L	1

Notes 1. This applies when the main-clock division selection bit = "0".

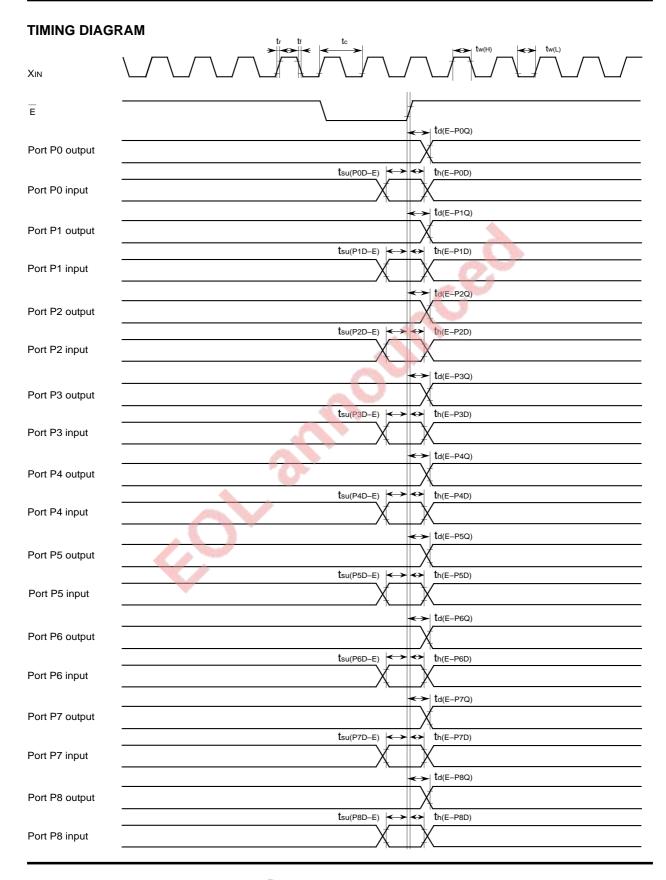
2. f(f2) represents the clock f2 frequency.

For the relation to the main clock and sub clock, refer to Table 10 in data sheet "M37735MHBXXXFP".



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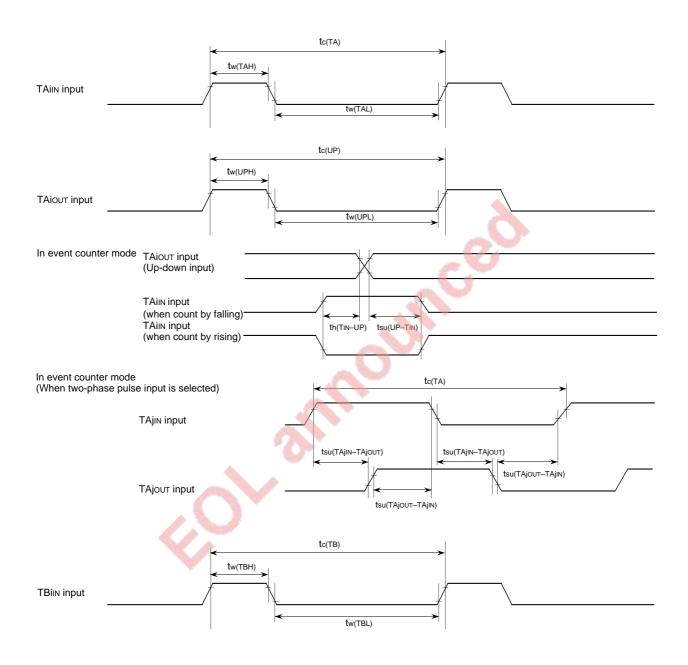
M37735EHBXXXFP M37735EHBFS





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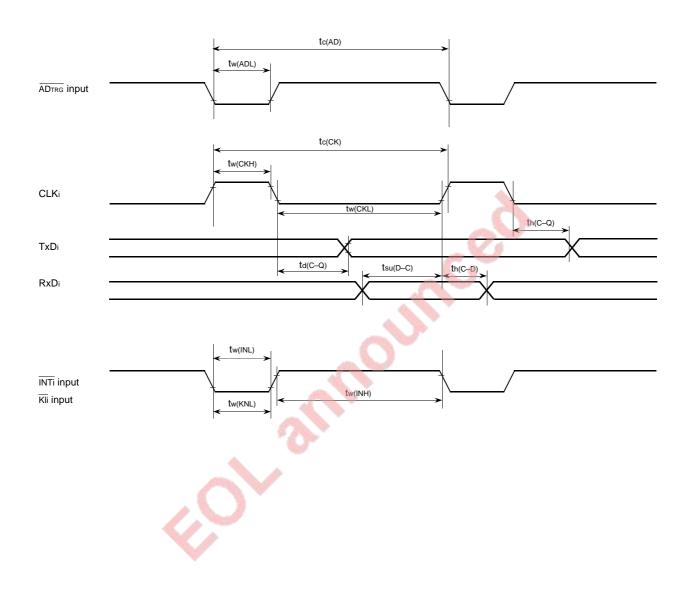
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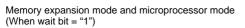
M37735EHBXXXFP M37735EHBFS

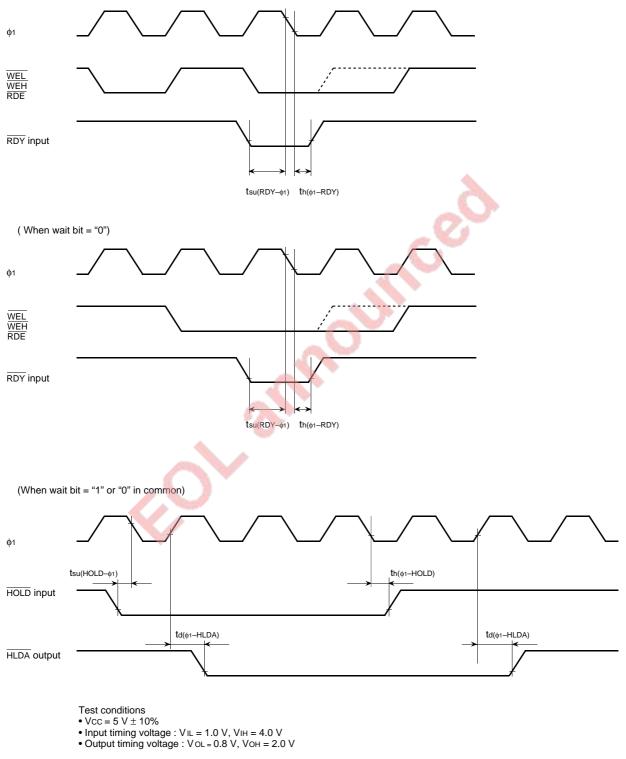




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M37735EHBXXXFP M37735EHBFS





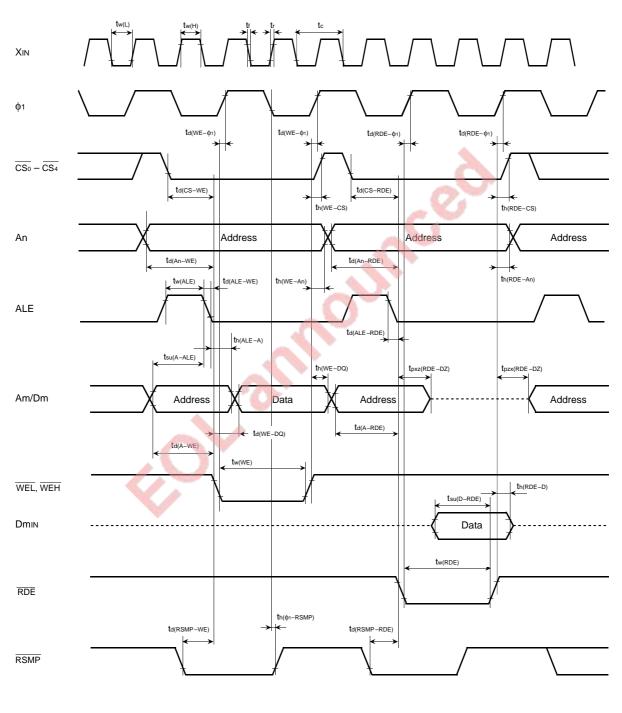


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M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

Memory expansion mode and microprocessor mode (No wait : When wait bit = "1")



Test conditions

• Vcc = 5 V ± 10%

• Output timing voltage : VoL = 0.8 V, VoH = 2.0 V

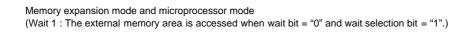
• Data input DmIN : VIL = 0.8 V, VIH = 2.5 V

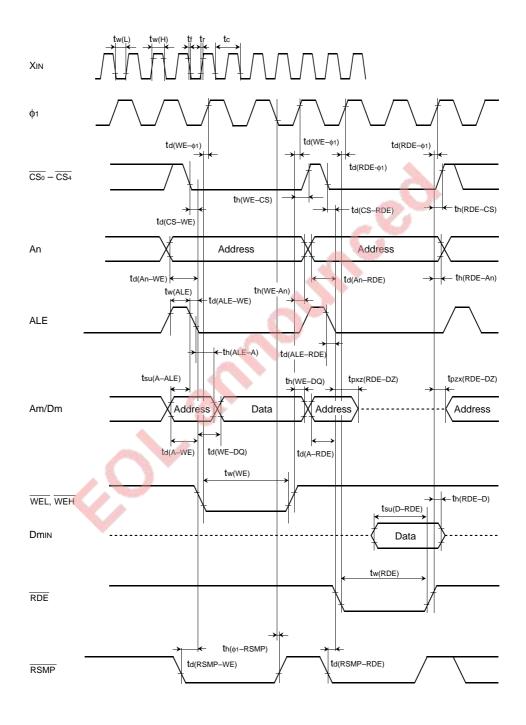


MITSUBISHI MICROCOMPUTERS

M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP





Test conditions

- Vcc = 5 V \pm 10%
- \bullet Output timing voltage : VoL = 0.8 V, VoH = 2.0 V
- Data input DmIN : VIL = 0.8 V, VIH = 2.5 V

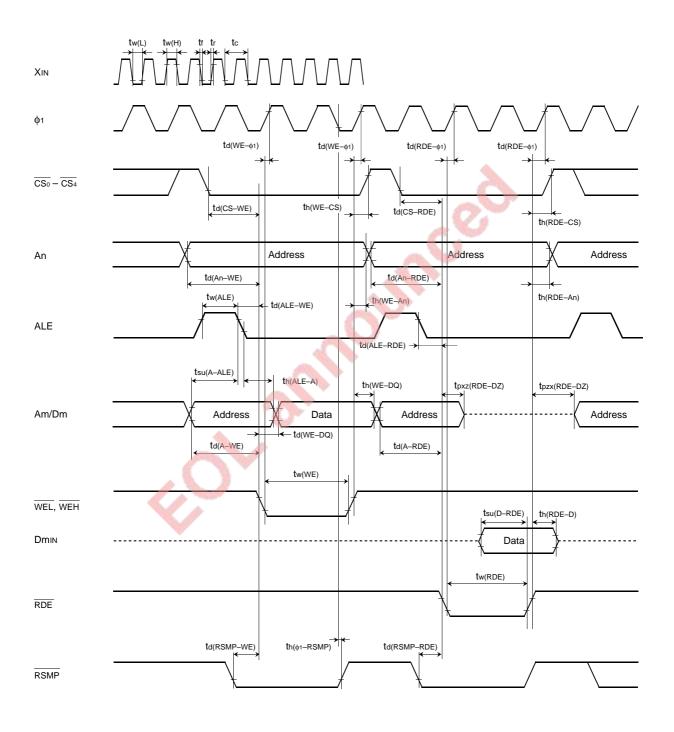


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M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

Memory expansion mode and microprocessor mode (Wait 0 : The external memory area is accessed when wait bit = "0" and wait selection bit = "0".)



Test conditions

• Vcc = 5 V ± 10%

- Output timing voltage : V $_{OL}$ = 0.8 V, V $_{OH}$ = 2.0 V

• Data input DmiN : VIL = 0.8 V, VIH = 2.5 V

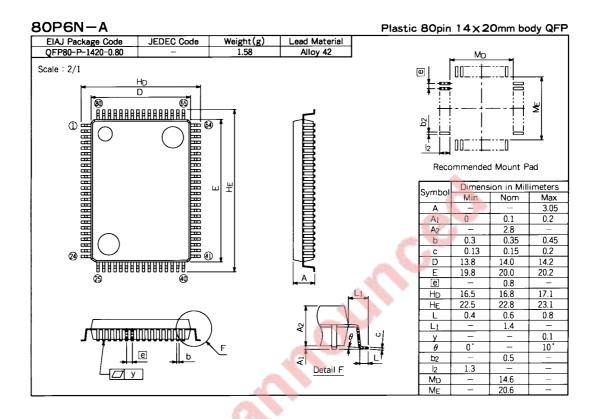




M37735EHBXXXFP M37735EHBFS

PROM VERSION OF M37735MHBXXXFP

PACKAGE OUTLINE





GZZ-SH00-81B<84A0>

7700 FAMILY WRITING TO PROM ORDER CONFIRMATION FORM SINGLE-CHIP 16-BIT MICROCOMPUTER M37735EHBXXXFP **MITSUBISHI ELECTRIC**

ROM number					
	Date:				
đ	Section head signature	Supervisor signature			
Receipt					

Note : Please fill in all items marked 💥

*	Customer _	Company name		TEL ()	nce ures	Responsible officer	Supervisor
		Date issued	Date:		2	Issuan signatu		

%1. Confirmation

Specify the name of the product being ordered and the type of EPROMs submitted.

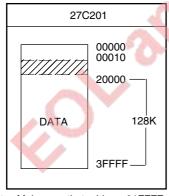
Three sets of EPROMs are required for each pattern.

If at least two of the three sets of EPROMs submitted contain the identical data, we will produce writing to PROM based on this data. We shall assume the responsibility for errors only if the written PROM data on the products we produce differ from this data. Thus, the customer must be especially careful in verifying the data contained in the EPROMs submitted.

Checksum code for entire EPROM areas

(hexadecimal notation)

EPROM Type :



Note : Make sure that address 01FFFF16 of the microcomputer's internal ROM corresponds to address 3FFFF16 of EPROM.

(1) Set "FF16" in the shaded area.

(2) Address 016 to 0F16 are the area for storing the data on model designation. This area must be written with the data shown below.

Address and data are written in hexadecimal notation.

	Address		Address
4D	0	42	8
33	1	FF	9
37	2	FF	Α
37	3	FF	В
33	4	FF	С
35	4 5	FF	D
45	6	FF	Е
48	7	FF	F

%2. Mark specification

Mark specification must be submitted using the correct form for the type of package being ordered fill out the appropriate 80P6N Mark Specification Form (for M37735EHBXXXFP) and attach to the Writing to PROM Order Confirmation Form. %3. Comments

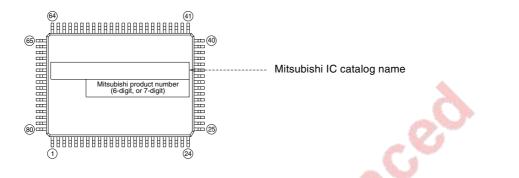


80P6N (80-PIN QFP) MARK SPECIFICATION FORM

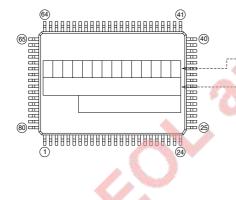
Mitsubishi IC catalog name

Please choose one of the marking types below (A, B, C), and enter the Mitsubishi IC catalog name and the special mark (if needed).

A. Standard Mitsubishi Mark



B. Customer's Parts Number + Mitsubishi IC Catalog Name

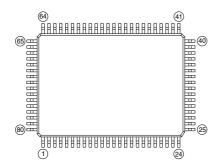


Customer's Parts Number

Note : The fonts and size of characters are standard Mitsubishi type. Mitsubishi IC catalog name

- Notes 1 : The mark field should be written right aligned.
 - 2 : The fonts and size of characters are standard Mitsubishi type.
 - 3 : Customer's parts number can be up to 14 alphanumeric characters for capital letters, hyphens, commas, periods and so on.

C. Special Mark Required



Notes1 : If special mark is to be printed, indicate the desired layout of the mark in the left figure. The layout will be duplicated technically as close as possible.

Mitsubishi product number (6-digit, or 7-digit) and Mask ROM number (3-digit) are always marked for sorting the products.

2 : If special character fonts (e,g., customer's trade mark logo) must be used in Special Mark, check the box below.

For the new special character fonts, a clean font original (ideally logo drawing) must be submitted.

Special character fonts required



PRELIMINARY Notice: This is not a final specification. Some parametric limits are subject to change

M37735EHBXXXFP **M37735EHBFS**

PROM VERSION OF M37735MHBXXXFP

RenesasTechnologyCorp.

Nippon Bldg.,6-2,Otemachi 2-chome,Chiyoda-ku,Tokyo,100-0004 Japan

Keep safety first in your circuit designs!

Misubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials -

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REVISION DESCRIPTION LIST

M37735EHBXXXFP, M37735EHBFS Datasheet

Rev. No.	Revision Description					
1.00	First Edition					
1.01	The following are added:			980526		
	PROM ORDER CONFIRMATION FORM					
	MARK SPECIFICATION FORM					
2.00	The following are revised:					
	Page	Previous Version	Revised Version			
	P12 Right column Line 2	The M37735EHBXXXFP has 28 powerful addressing modes. Refer to the MITSUBISHI SEMICONDUCTORS DATA BOOK SINGLE- CHIP 16-BIT MICROCOMPUTERS for the details of each addressing mode. MACHINE INSTRUCTION LIST The M37735EHBXXXFP has 103 machine instructions. Refer to the MITSUBISHI SEMICONDUCTORS DATA BOOK SINGLE- CHIP 16-BIT MICROCOMPUTERS for details.	The M37735EHBXXXFP has 28 powerful addressing modes. <u>Refer to the "7700 Family</u> <u>Software Manual" for the details.</u> MACHINE INSTRUCTION LIST The M37735EHBXXXFP has 103 machine instructions. <u>Refer to the "7700 Family Software</u> <u>Manual" for the details.</u>			

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